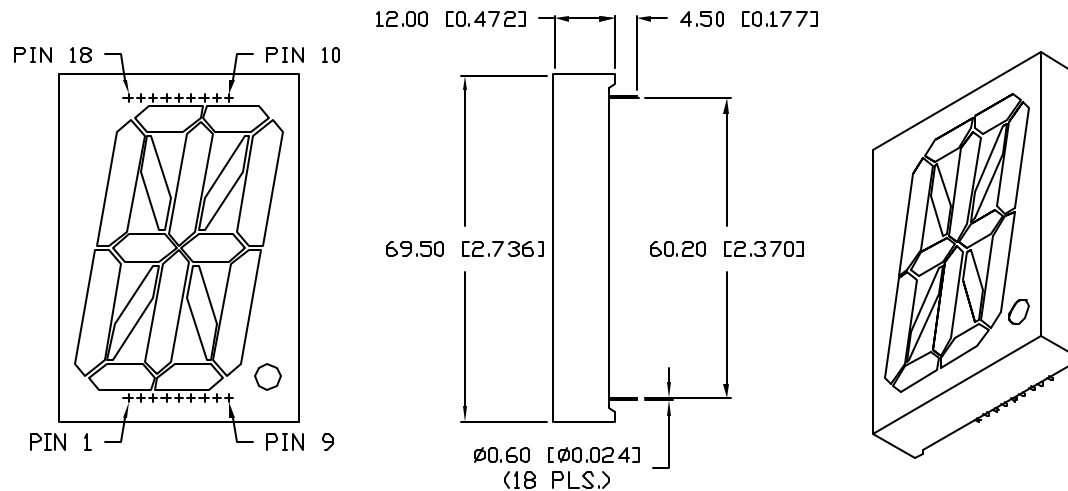


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REV.



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=10\text{mA}$

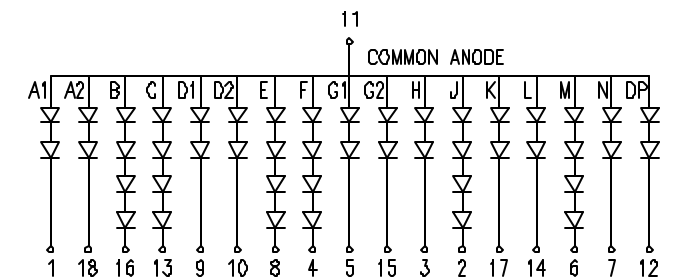
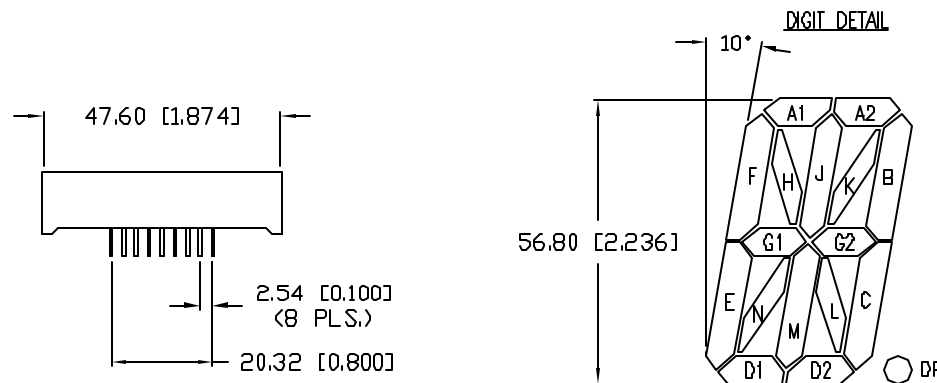
| PARAMETER | MIN | TYP | MAX | UNITS | TEST COND |
|------------------|----------------------|---------|----------|----------------|----------------------|
| PEAK WAVELENGTH | | 636 | | nm | |
| FORWARD VOLTAGE* | | 4.0/8.0 | 5.0/10.0 | V _f | |
| REVERSE VOLTAGE | 5.0 | | | V _r | $I_f=100\mu\text{A}$ |
| AXIAL INTENSITY | | 13000 | | μcd | $I_f=10\text{mA}$ |
| EMITTED COLOR: | RED | | | | |
| FACE COLOR: | GRAY | | | | |
| SEGMENT COLOR: | MILKY WHITE DIFFUSED | | | | |

* SECOND VALUE FOR FOUR CHIPS IN B,C,E,F,J,M.

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

| PARAMETER | MAX | UNITS |
|--------------------------|------------|------------|
| PEAK FORWARD CURRENT* | 150 | mA |
| STEADY CURRENT | 30 | mA |
| POWER DISSIPATION | 105 | mW |
| DERATE FROM 25°C | -1.6 | mW/°C |
| OPERATING, STORAGE TEMP. | -40 TO +85 | °C |
| SOLDERING TEMP. | +260 | °C |
| 2.0mm FROM BODY | | 3 SEC. MAX |

* $t < 10\mu\text{s}$



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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN= ^{+DECIMAL PRECISION} _{-0.00} MAX.= ^{+0.00} _{-DECIMAL PRECISION}

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2.3" SINGLE DIGIT, 16 SEGMENT LED DISPLAY,
636nm RED CHIPS, GRAY FACE WITH WHITE SEGMENTS,
COMMON ANODE, 18 PINS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC CHECKED BY: APPROVED BY: DATE: 7.18.03
PAGE: 1 OF 1
SCALE: N/A